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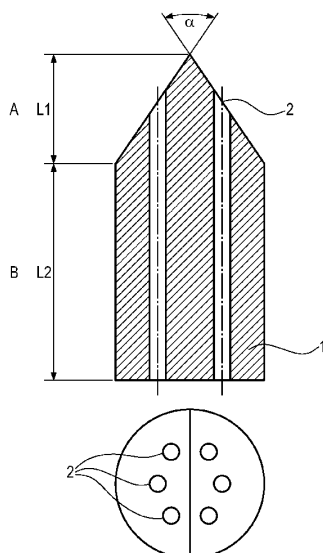
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- (54) **Title:** IMPROVED DEVICE FOR DRYING SEMICONDUCTOR SUBSTRATES

Fig. 1



- (57) **Abstract:** Device for drying disc-shaped substrates comprising an elongated body (1), which tapers upwards to form a wedge (A) having an angle α between two surfaces and an upper edge wherein the upper edge is suitable for holding the disc-shaped substrates, characterized in that the two surfaces comprise more than one holes (2) each forming channels, which extend to a lower drainage part (B) of the elongated body.

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